10th MiNaPAD
Micro/Nano-Electronics Packaging & Assembly, Design and Manufacturing Forum
June 7-8, 2023 – Grenoble, France

Call for extended abstracts

Extended Abstracts (2 pages typical, including graphs, pictures, ...) are requested on the following topics:

**Advanced packaging:**
TSVs, 2.5 & 3D interposers, wafer level packaging, embedded IC packages, SiP, PoP, MEMS packaging, power packaging, advanced substrates, Hybrid bonding, Fan Out wafer and panel level processes.

**Assembly and manufacturing technologies:**
Bonding, advanced dicing, flux, cleaning, dispensing, coating technologies, materials & equipment related to assembly manufacturing and business aspects of the industry.

**Advanced interconnections:**
Flip-chip including ultra-fine pitches approaches, interconnections, IMC studies, bumping techniques (solder bumps, Cu pillars,...) disruptive interconnections, optical connections.

**Emerging & sustainable technologies & applications:**
Flexible/stretchable packaging, nanomaterial for interconnections, green/bio and sustainable technologies for packaging, additive manufacturing, Nano manufacturing.

**Innovative Materials equipment’s and processes:**
3D materials, conductive & non-conductive adhesives, underfill, molding, disruptive solder alloys, thermal interface. Innovative equipment for assembly & packaging.

**Packaging & Assembly Reliability:**
Applied reliability for LED, Displays, IoT, MEMS, memories, medical devices, chip-package and package-PCB interaction. Life models, failure analysis techniques & characterizations.

**Imaging & photonics assembly technologies:**
Assembly & packaging technologies for optical and photonics applications: imaging, displays, silicon photonics, optical sensors, high energy physics and medical imaging.

**Thermal/mechanical simulation and characterization:**
Components, boards & system level modelling for: interconnections, interposers, substrates, WLP & embedded packages, power modules, optical packaging, RF and MEMS.
Practical information

Organization:
IMAPS France
Email: imaps.france@orange.fr
Web: www.france.imapseurope.org

General chair: Jean-Marc YANNOU (ASE)
Technical Chairs:
Sanae BOULAY (NXP),
Jean-Luc DIOT (Assemblinnov),
Romain COFFY (ST Microelectronics),
Jean-Charles SOURIAU (CEA-LETI),
Christophe ZINCK (ASE),
Laurent MENDIZABAL (CEA-LETI),
Alexandre VAL (VALEO).

Location: Close to Grenoble Railway Station
WTC / Congress center
5 -7, place Robert Schuman – BP 1521
38025 Grenoble Cedex 1
FRANCE

Exhibition area:
Equipment & Product suppliers in the WTC Atrium
during the workshop

Important dates

Extended abstracts submission date:
From November 24th, 2022 to March 6th, 2023
Your submission must include the mailing address,
business phone number and email address and the
content must be without commercial information.

Address your abstract to:
imaps.france@orange.fr

Notification of acceptance:
Authors will be notified of paper acceptance with
instructions for presentation before March 28th, 2023.

Presentations:
Presentation should be ready one day before the
workshop and supply to the chairwomen or
chairmen of your session.

Social event:
Evening dinner & visit on the 7th of June 2023

Sponsored by